



设备用途和特性

- ## Applications and structural features

The machine is used for cutting semi-conductor bar which is mainly used in processing equipment. The max dimension of cross section of silicon, the minimum thickness of silicon 0.2mm, adjust the speed of cutting, protect it may cut 0.02mm, adjust the clamp, the optimized equipment for semi-conductor manufacturers.

- **fast, accurate, reliable**
- **two wire guide wheel drive** (cable drive, 'cable' drive, all or base drive, servo drive, and must be synchronized)
- **detection control of wire tension** (of wire controlled by 'servo motor' by same motor (consistently) (constant))
- **workpiece feeding** (servo motor and the ball screw can feed rate here is matched guiding speed of wire)
- **heating and conveying of cutting fluid** (cutting fluid pipe, can reach up constant temperature through heat exchanger, match the sliding rate)
- **this machine is an integrated high-tech product.**

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